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Abstract of the Disclosure

[0059] A electroplating apparatus which is suitable for depositing a metal layer of substantially uniform thickness across the center and edge regions of a semiconductor wafer substrate is disclosed. The apparatus includes a reservoir for containing an electrolytic fluid. A cathode, to which is mounted a wafer, and an anode in the electrolytic fluid are connected to an electroplating current source. A shield is provided between the cathode and anode to facilitate a more uniform deposit of the metal onto the wafer across the entire surface, including the center and edge regions, of the wafer.